# DUSEU

# **MOSFET** - Power, N-Channel, SUPERFET<sup>®</sup> III, **FRFET**<sup>®</sup>

## 650 V, 82 mΩ, 40 A NVHL082N65S3HF

#### Description

SUPERFET III MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III HF version provides fast recovery for improved efficiency in high speed switching applications.

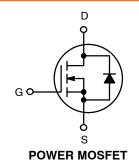
#### Features

- 700 V @ T<sub>J</sub>= 150°C
- Typ.  $R_{DS(on)} = 70 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 78 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 678 pF)
- 100% Avalanche Tested
- NVHL Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### Applications

- Automotive On Board Charger HEV-EV
- Automotive DC/DC Converter for HEV-EV

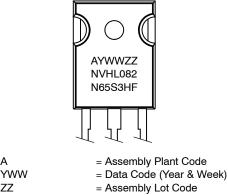
V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	82 mΩ @ 10 V	40 A





TO-247 Long Leads CASE 340CX

#### **MARKING DIAGRAM**



ΖZ NVHL082N65S3HF = Specific Device Code

Α

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit		
V <sub>DSS</sub>	Drain-to-Source Voltage		650	V	
V <sub>GSS</sub>	Gate-to-Source Voltage	– DC	±30	V	
		– AC (f > 1 Hz)	±30		
I <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	40	А	
		– Continuous (T <sub>C</sub> = 100°C)	25.5	1	
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	100	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		510	mJ	
I <sub>AS</sub>	Avalanche Current (Note 2)		4.8	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		3.13	mJ	
dv/dt	MOSFET dv/dt Peak Diode Recovery dv/dt (Note 3)		100	V/ns	
			50		
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	313	W	
		- Derate Above 25°C	2.5	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		–55 to +150	°C	
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C	

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 4.8 \text{ A}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}C$ . 3.  $I_{SD} \le 20 \text{ A}$ , di/dt  $\le 200 \text{ A}/\mu \text{s}$ ,  $V_{DD} \le 400 \text{ V}$ , starting  $T_J = 25^{\circ}C$ .

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	

#### PACKAGE MARKING AND ORDERING INFORMATION

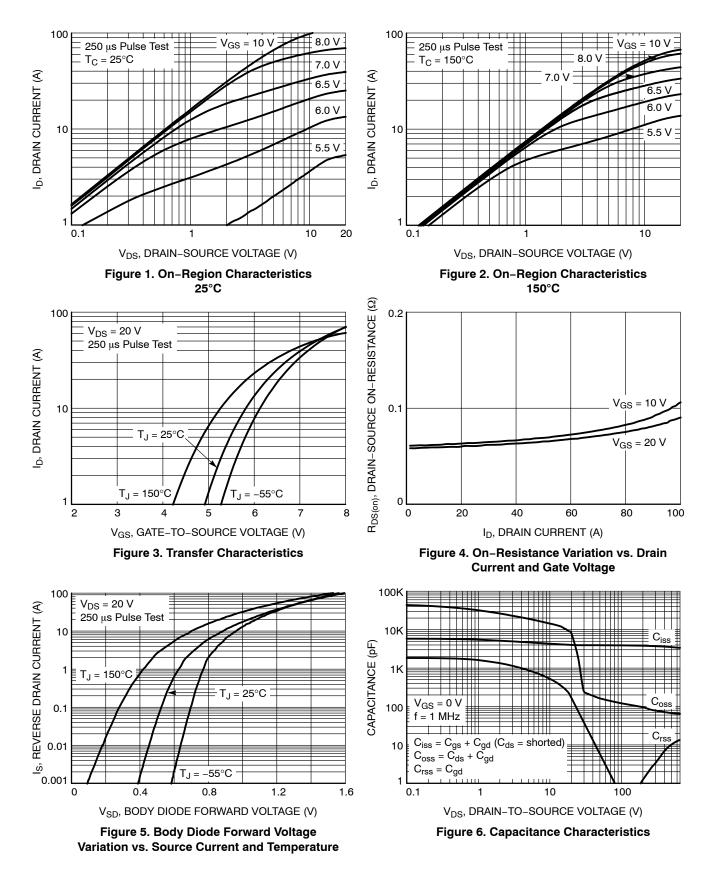
Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NVHL082N65S3HF	NVHL082N65S3HF	TO-247	Tube	N/A	N/A	30 Units

### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

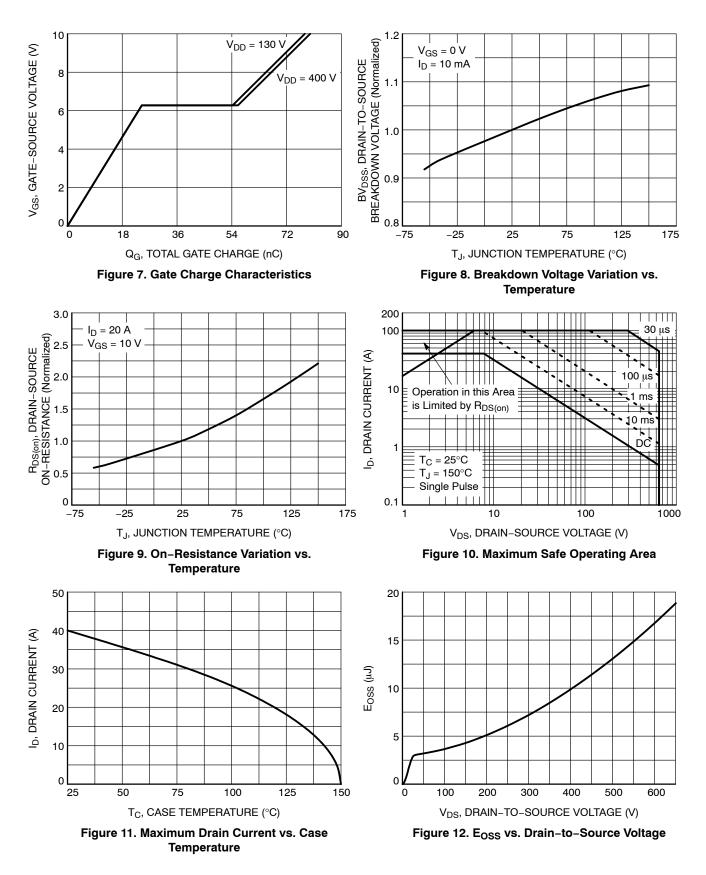
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	TERISTICS		•	•	-	•
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25°C	650	-	-	V
		$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	700	_	-	V
$\Delta \text{BV}_{\text{DSS}}  /  \Delta \text{T}_{\text{J}}$	J Breakdown Voltage Temperature I <sub>D</sub> = 10 mA, Reference Coefficient		_	0.7	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 650 V, $V_{GS}$ = 0 V	-	-	10	μA
		$V_{DS}$ = 520 V, $T_{C}$ = 125°C	-	13	-	1
I <sub>GSS</sub>	Gate-to-Body Leakage Current	$V_{GS}$ = ±30 V, $V_{DS}$ = 0 V	-	-	±100	nA
ON CHARACTI	ERISTICS	-			•	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	3.0	_	5.0	V
R <sub>DS(on)</sub>	Static Drain-to-Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	-	70	82	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	22	-	S
DYNAMIC CHA	RACTERISTICS					
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 1 MHz	-	3627	-	pF
Coss	Output Capacitance		-	71	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	678	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	127	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}$	-	78	-	nC
Q <sub>gs</sub>	Gate-to-Source Gate Charge	(Note 4)	-	24	-	nC
Q <sub>gd</sub>	Gate-to-Drain "Miller" Charge		-	29	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.8	-	Ω
SWITCHING CI	HARACTERISTICS					-
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 20 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	30.8	-	ns
t <sub>r</sub>	Turn-On Rise Time	R <sub>g</sub> = 4.7 Ω, (Note 4)	-	23.8	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	82.0	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	12.3	-	ns
SOURCE-DRA	IN DIODE CHARACTERISTICS					-
۱ <sub>S</sub>	Maximum Continuous Source-to-Drain Diode Forward Current			-	40	Α
I <sub>SM</sub>	Maximum Pulsed Source-to-Drain Diode Forward Current		-	_	100	Α
$V_{SD}$	Source-to-Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 20 \text{ A}$	_	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{DD} = 400 \text{ V}, I_{SD} = 20 \text{ A},$	-	102	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/µs	-	422	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

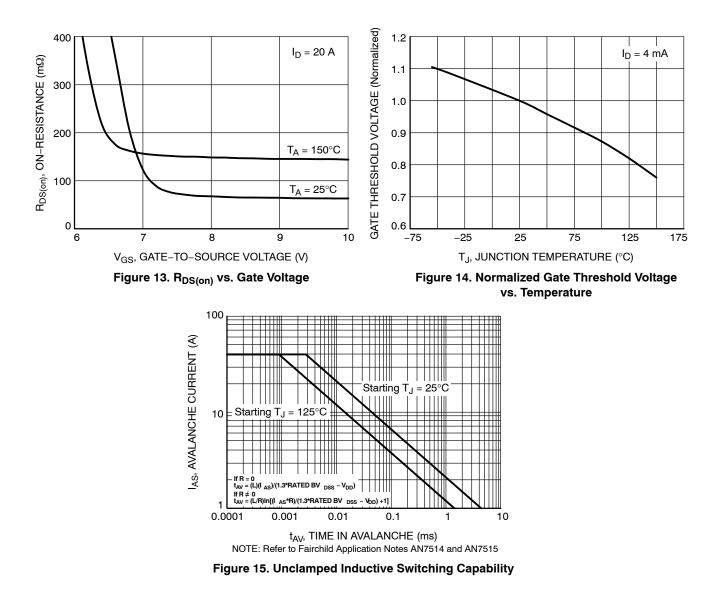
#### **TYPICAL CHARACTERISTICS**



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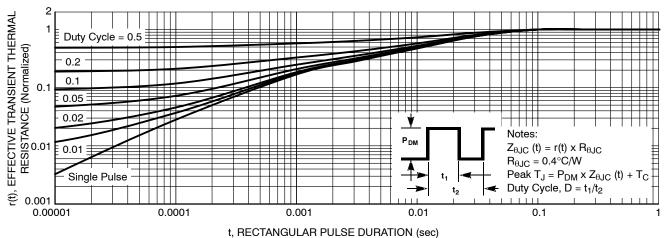
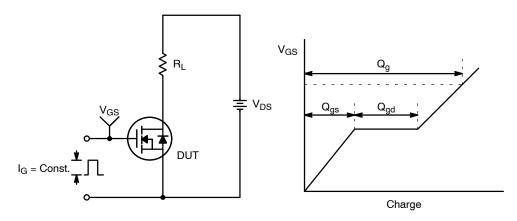


Figure 16. Transient Thermal Response





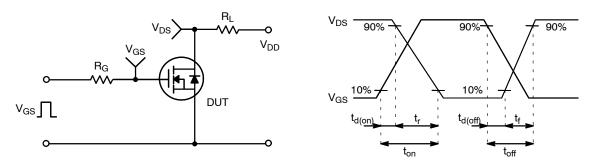
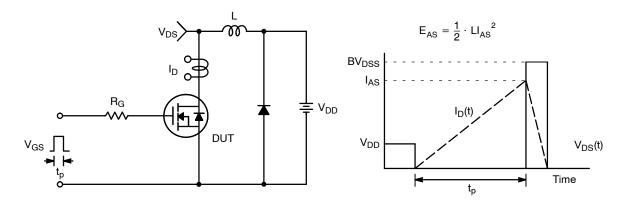


Figure 18. Resistive Switching Test Circuit & Waveforms





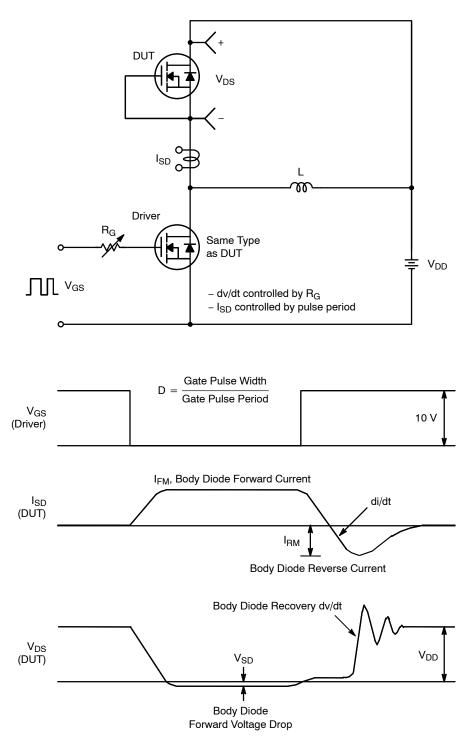
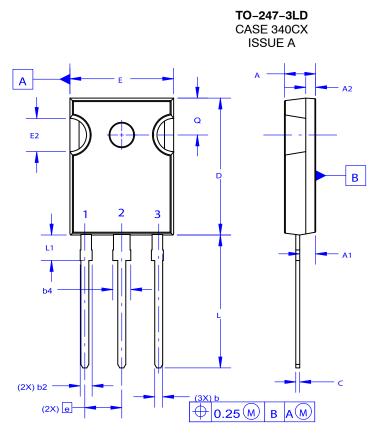


Figure 20. Peak Diode Recovery dv/dt Test Circuit & Waveforms

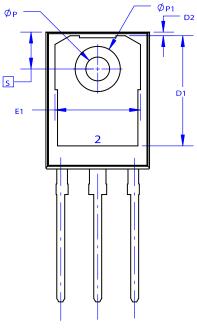
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#### PACKAGE DIMENSIONS



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
  D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
E	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
Ø <b>P</b> 1	6.60	6.80	7.00		

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